

FIG. 1
RELATED ART

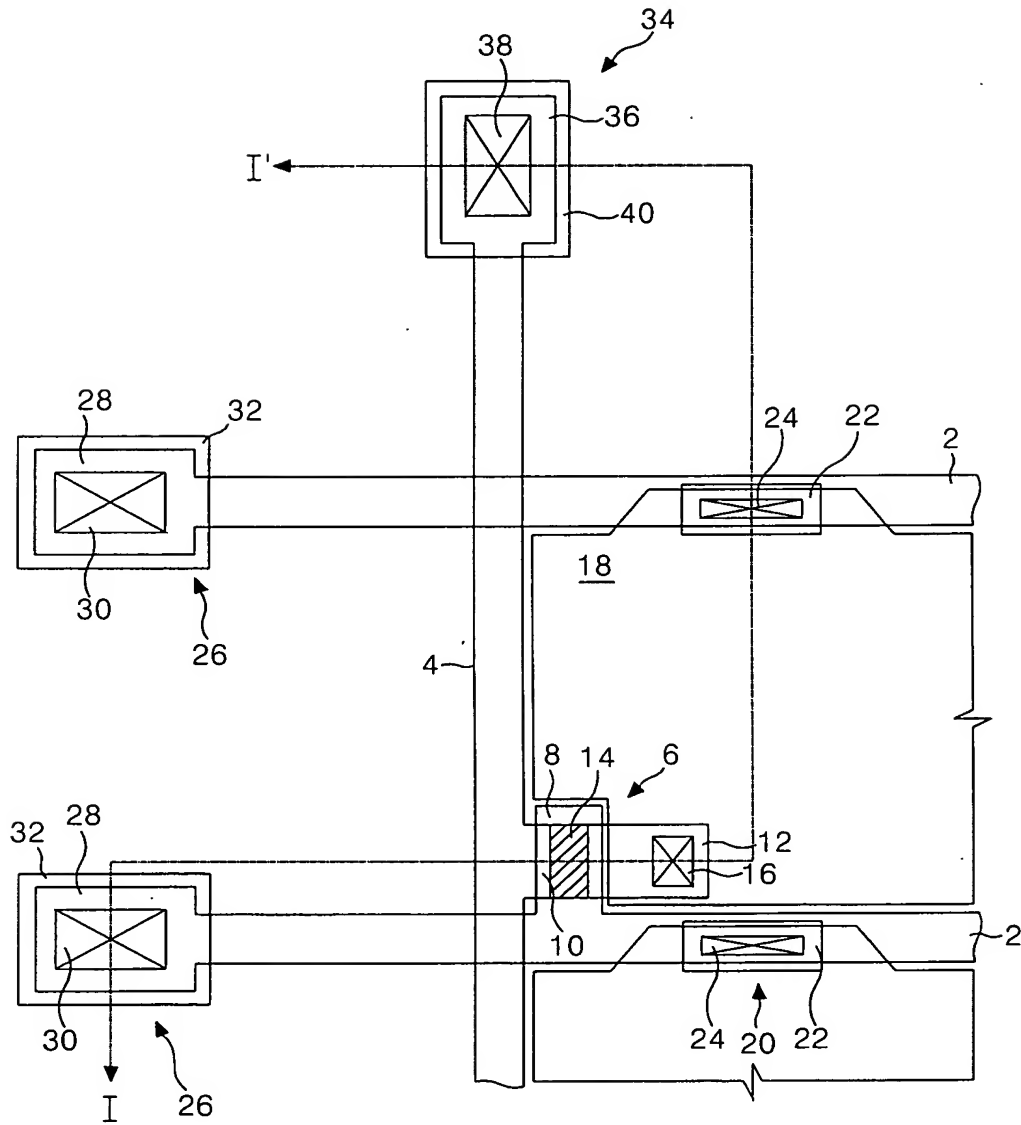


FIG. 2
RELATED ART

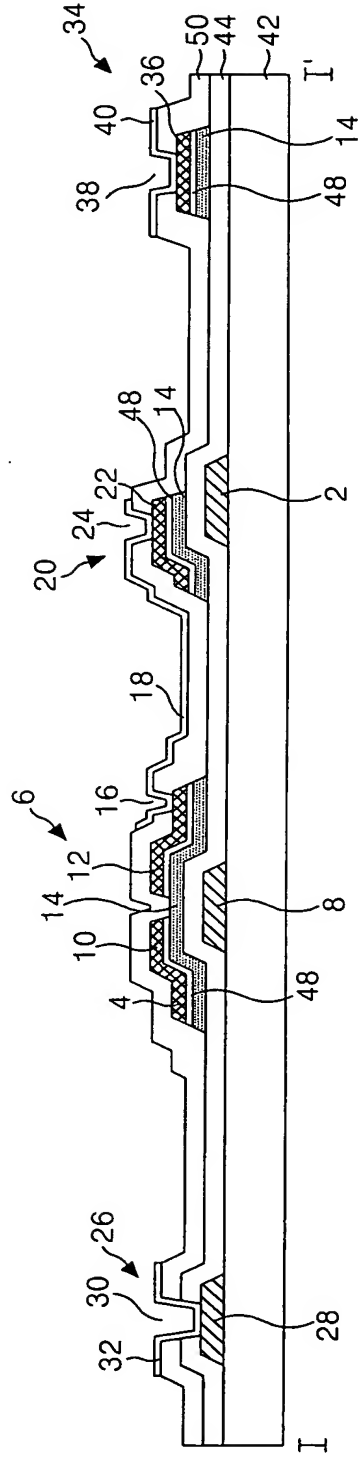


FIG. 3A
RELATED ART

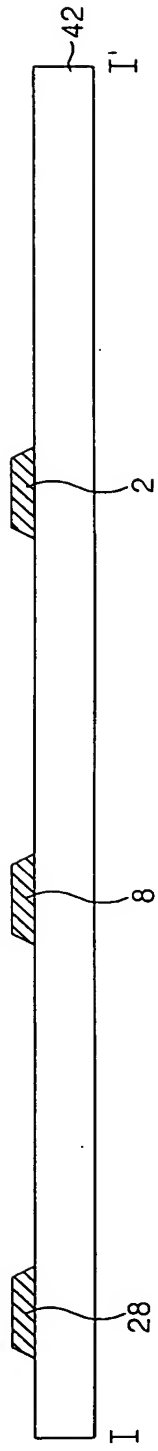


FIG. 3B
RELATED ART

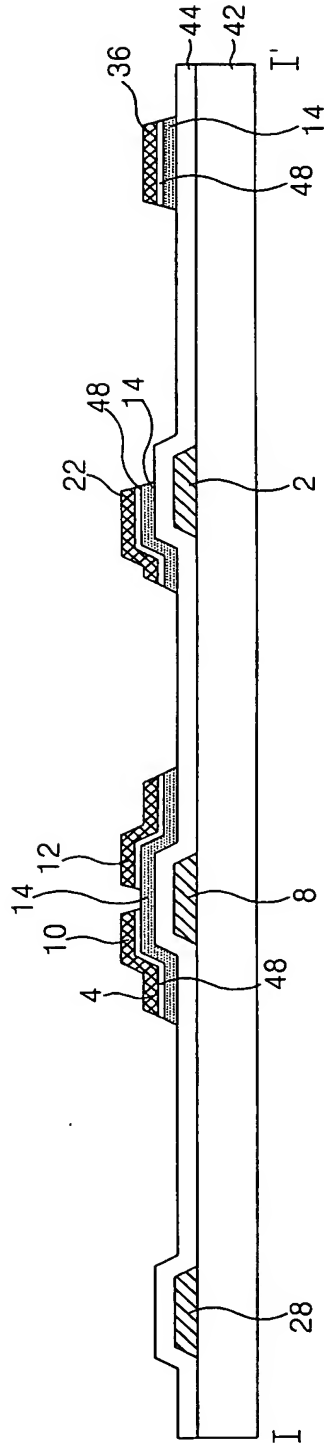
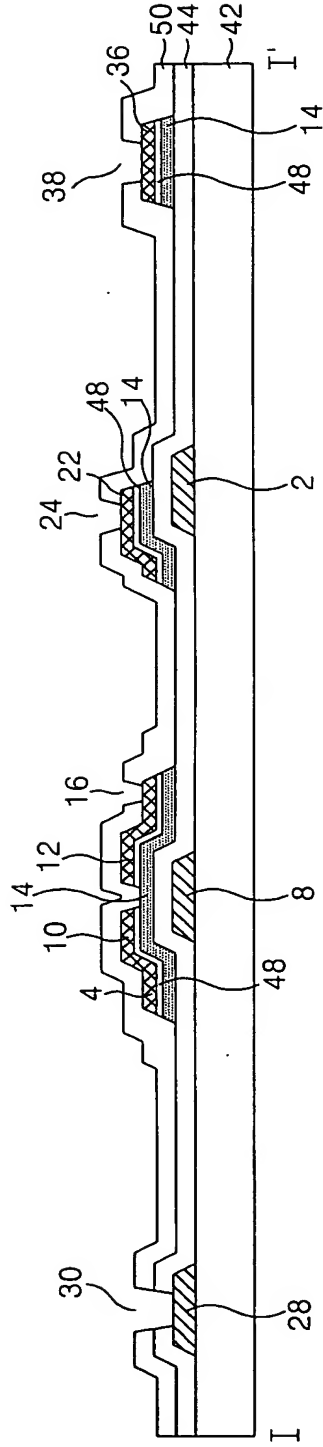


FIG. 3C
RELATED ART



This diagram shows a cross-sectional view of a multi-layered electronic device. A central substrate, labeled 2, is shown with a longitudinal section line I-I' passing through it. The device consists of multiple layers and structures on both the top and bottom surfaces of the substrate. On the top surface, there are conductive layers 4, 6, 8, 10, 12, 14, 16, 18, 20, 22, 24, 26, 28, 30, 32, 34, 36, 38, 40, 42, 44, 46, 48, and 50. These layers are separated by insulating layers 1, 3, 5, 7, 9, 11, 13, 15, 17, 19, 21, 23, 25, 27, 29, 31, 33, 35, 37, 39, 41, 43, 45, 47, and 49. The layers are patterned to form various electrical connections and components. The bottom surface of the substrate 2 also features a series of conductive layers and insulating layers, mirroring the top surface structure. The overall design suggests a complex, multi-layered circuit board or a similar electronic component.

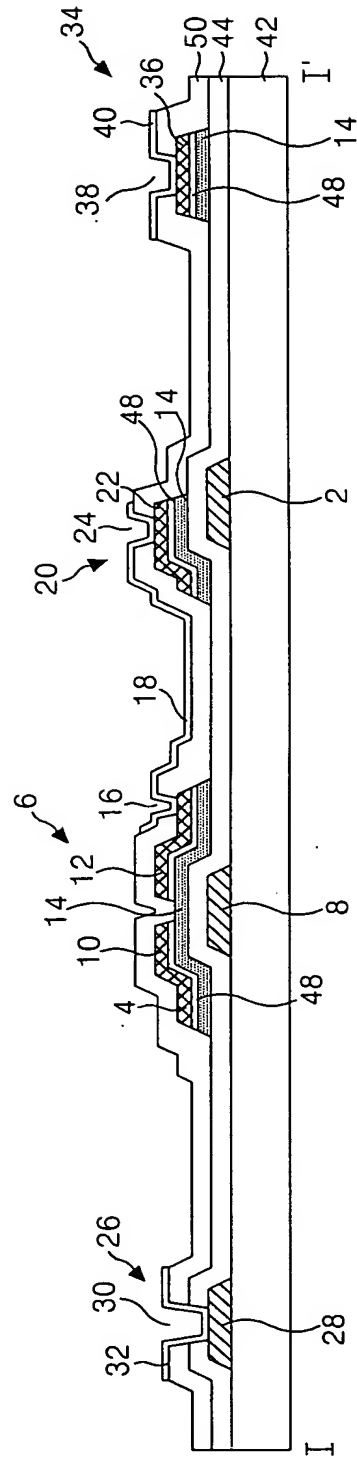


FIG. 4A

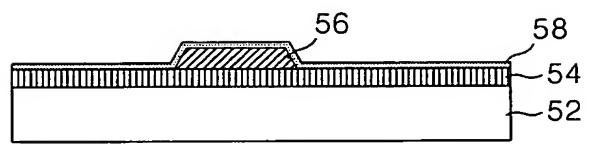


FIG. 4B

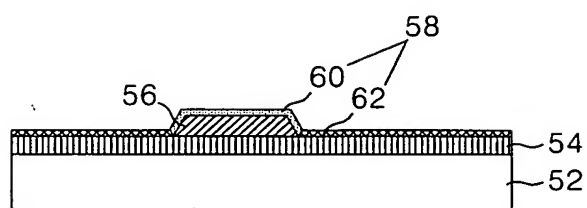


FIG. 4C

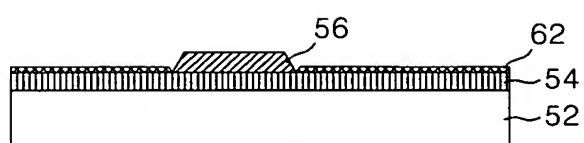


FIG. 5A

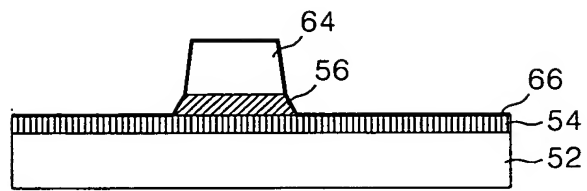


FIG. 5B

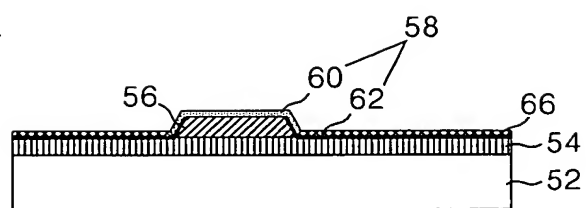


FIG. 5C

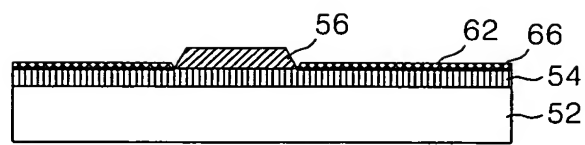


FIG. 6A

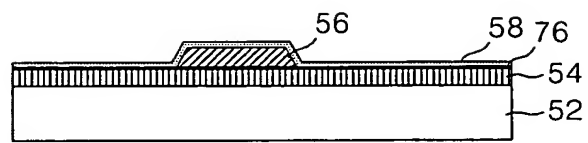


FIG. 6B

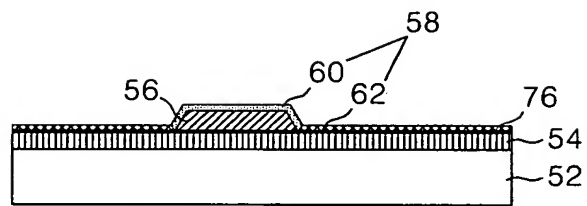


FIG. 6C

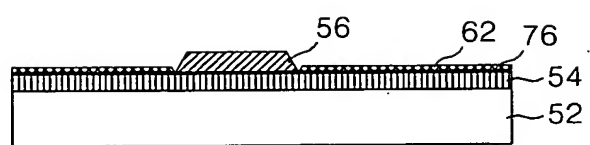


FIG. 7

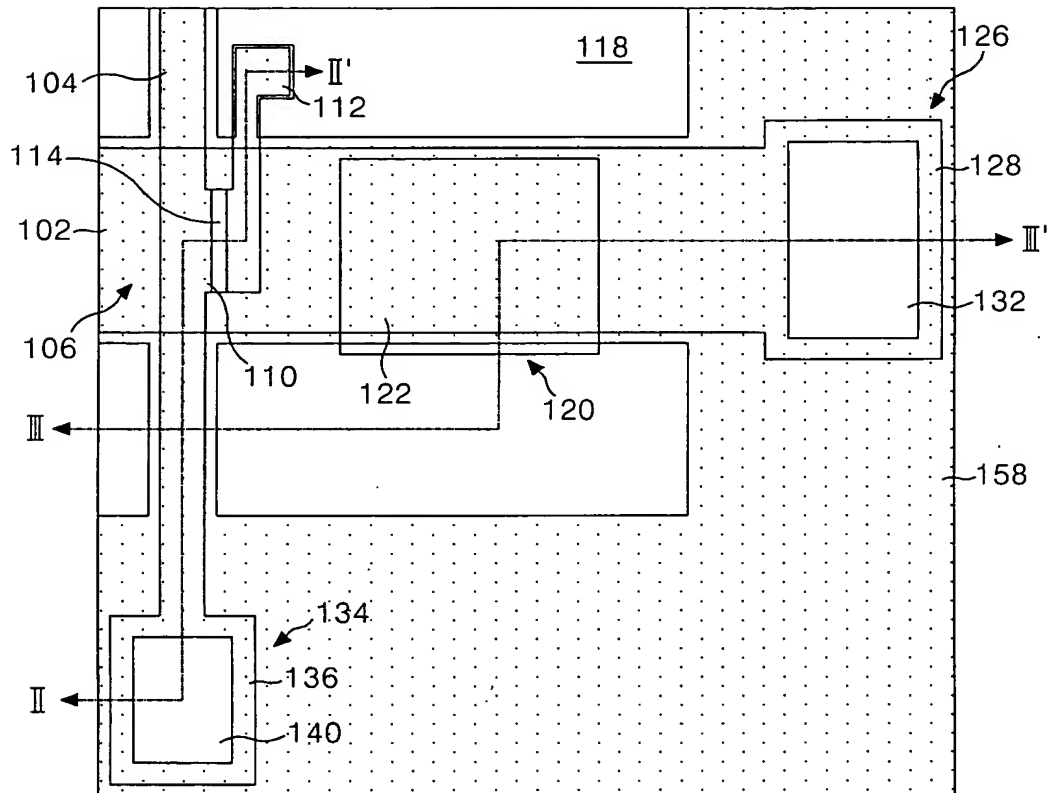


FIG.8

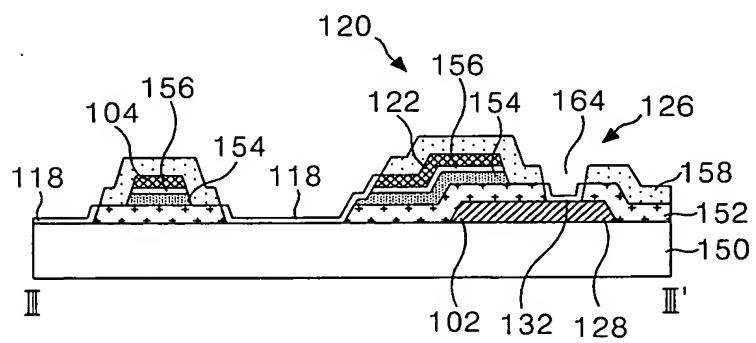
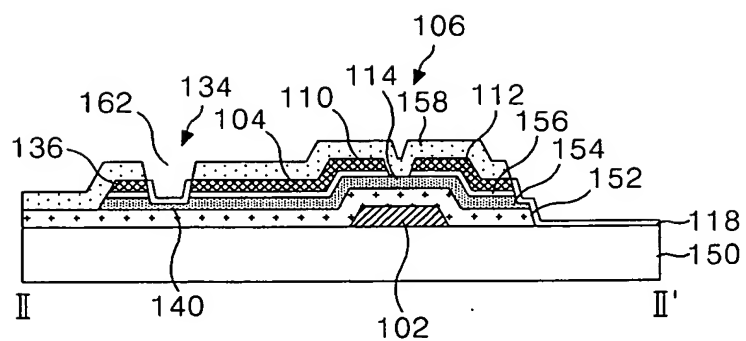


FIG.9A

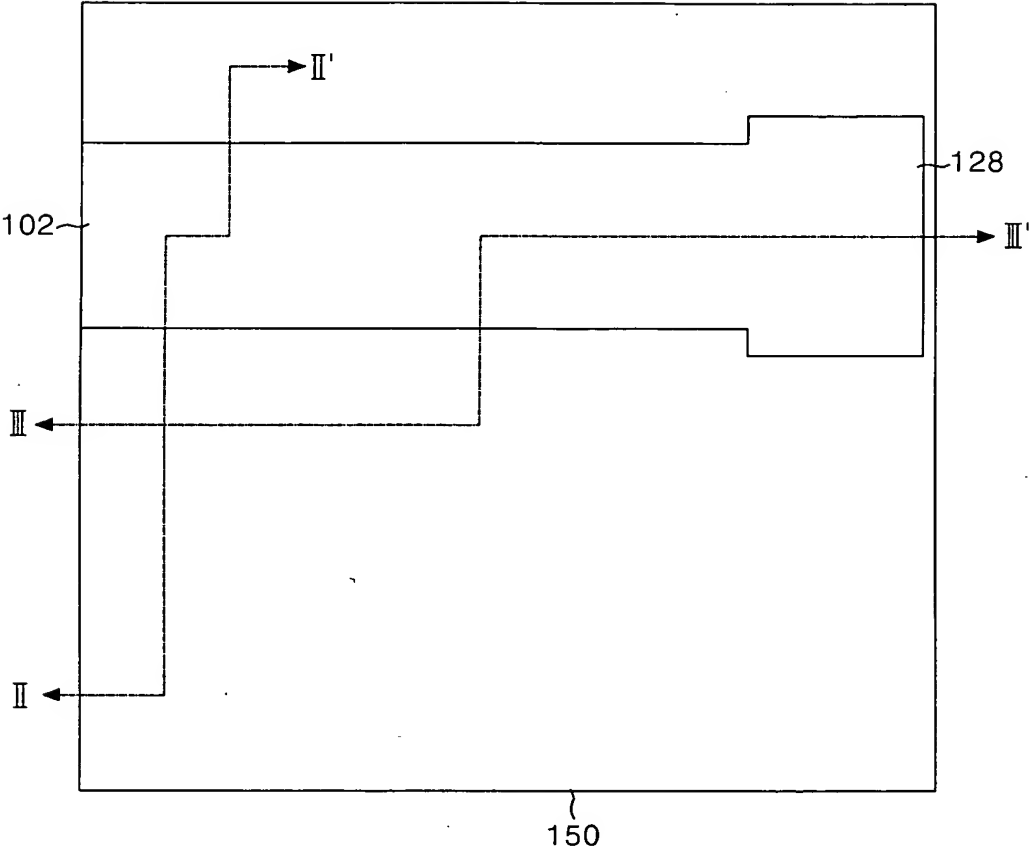


FIG. 9B

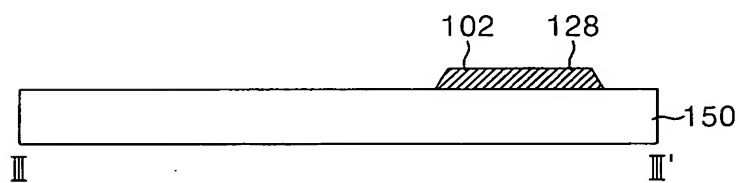
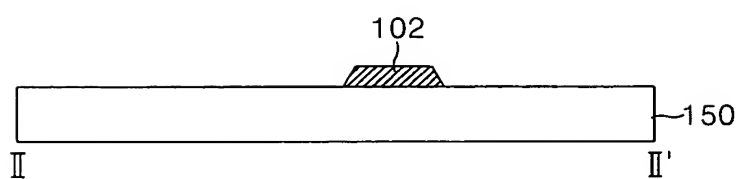


FIG. 10A

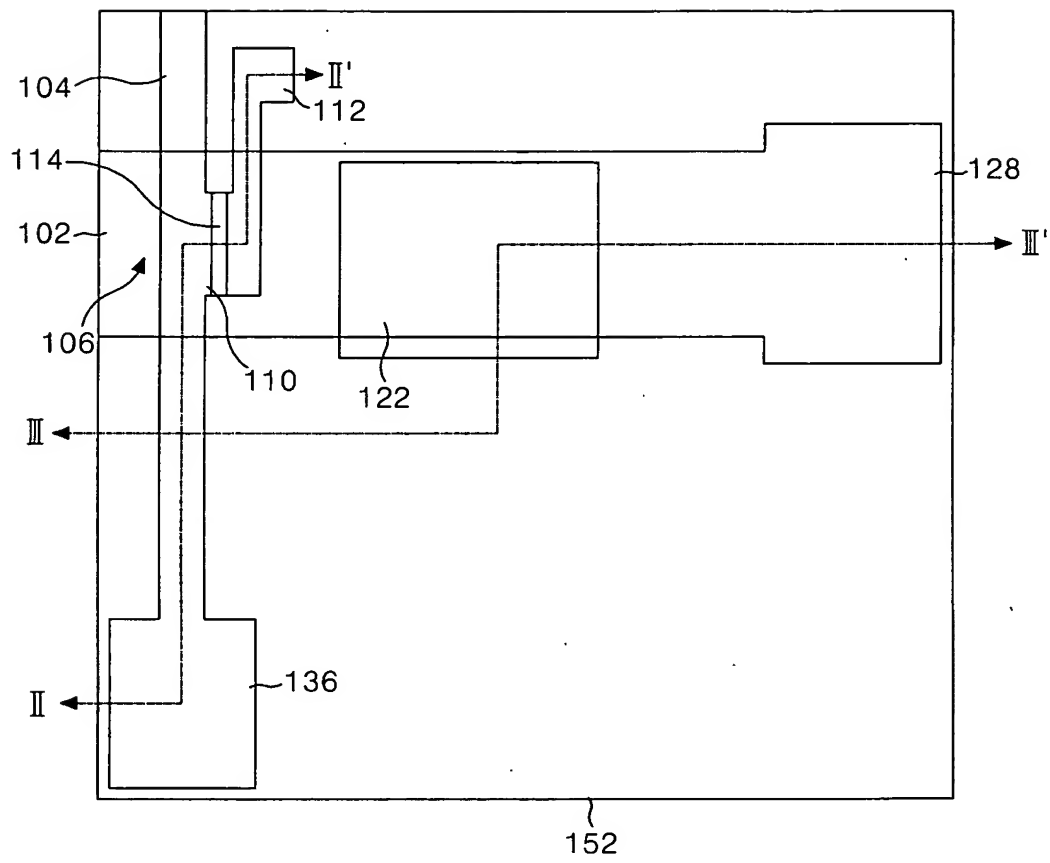


FIG. 10B

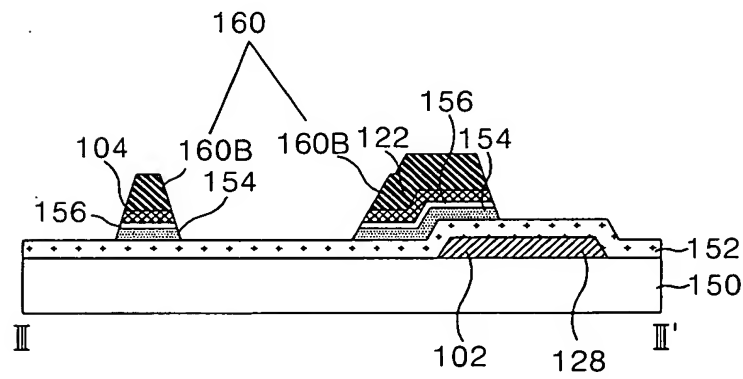
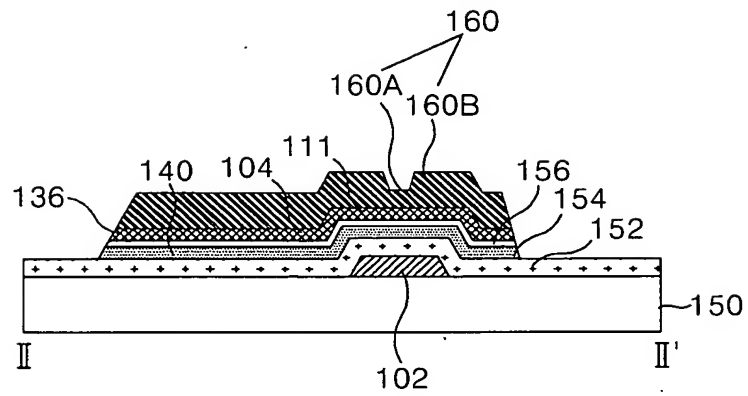


FIG. 10C

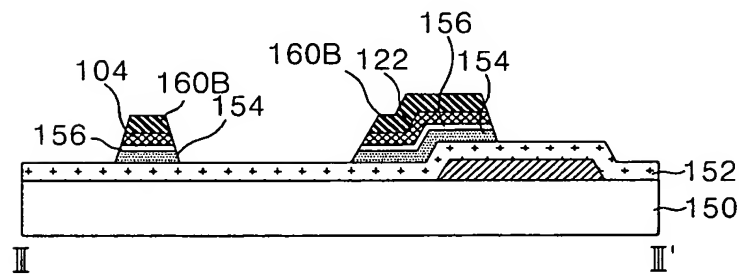
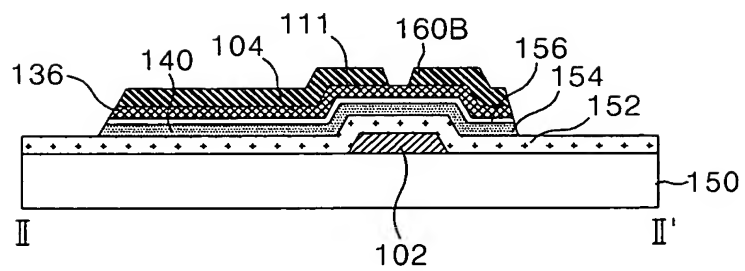


FIG. 10D

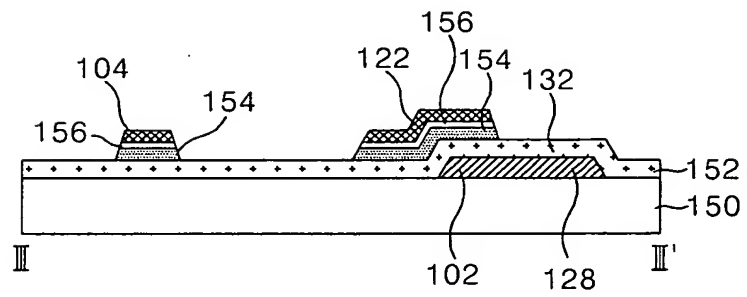
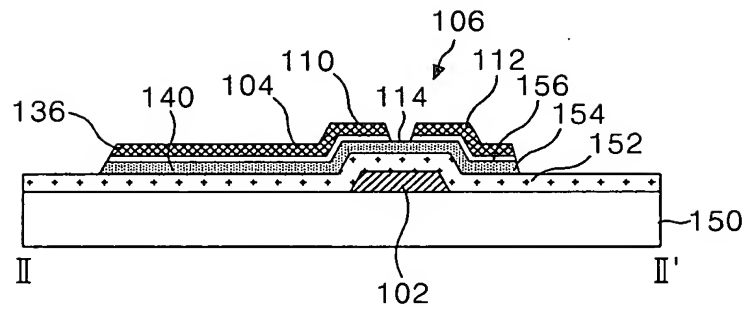


FIG. 11A

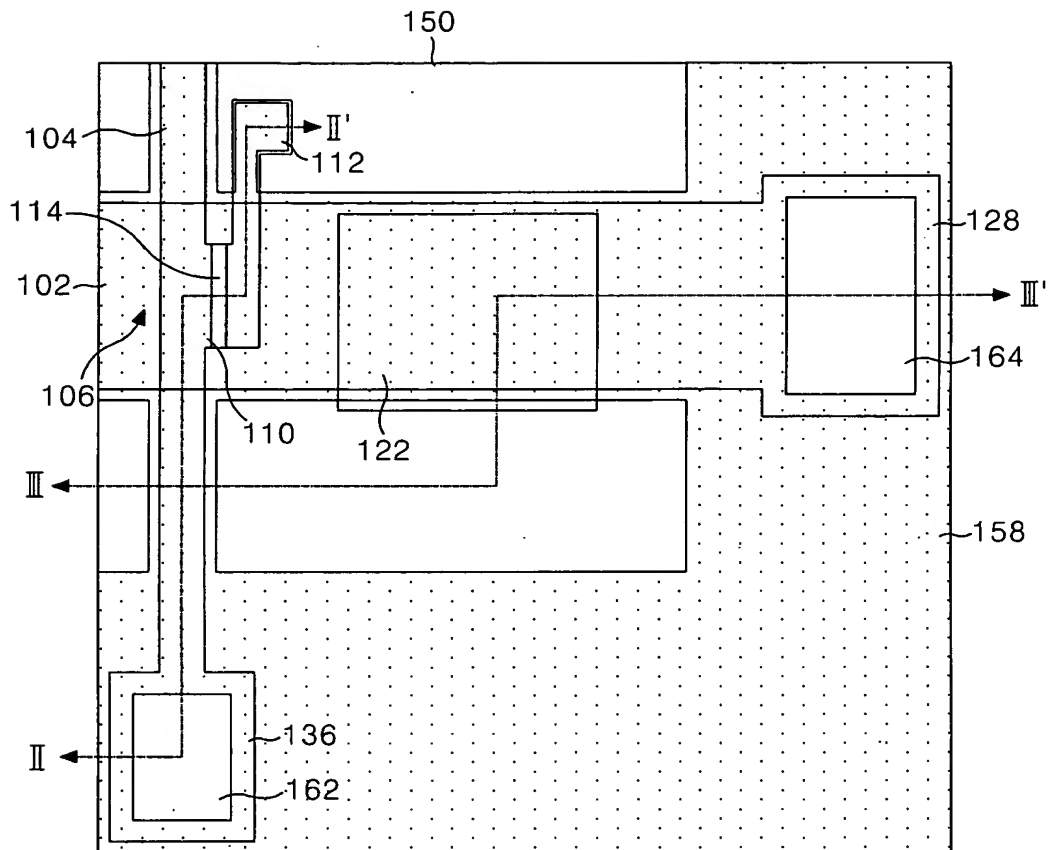


FIG. 11B

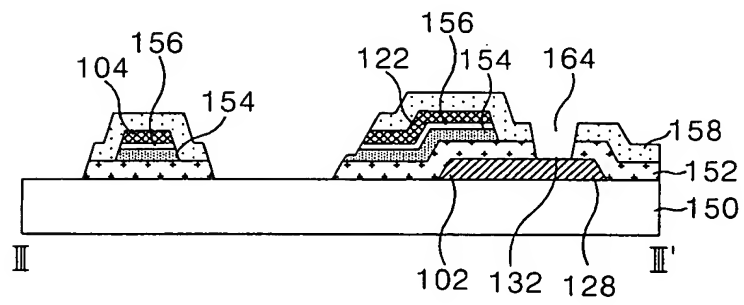
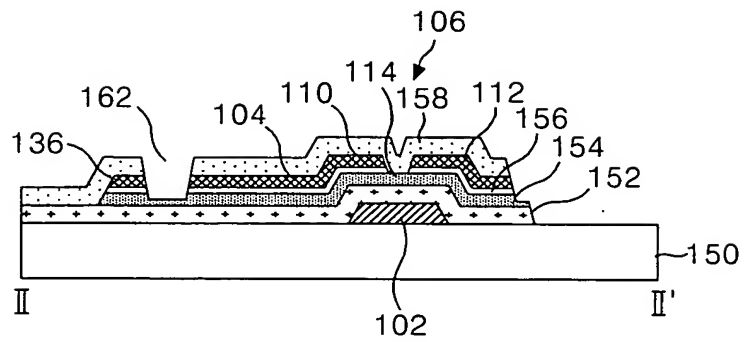


FIG.12A

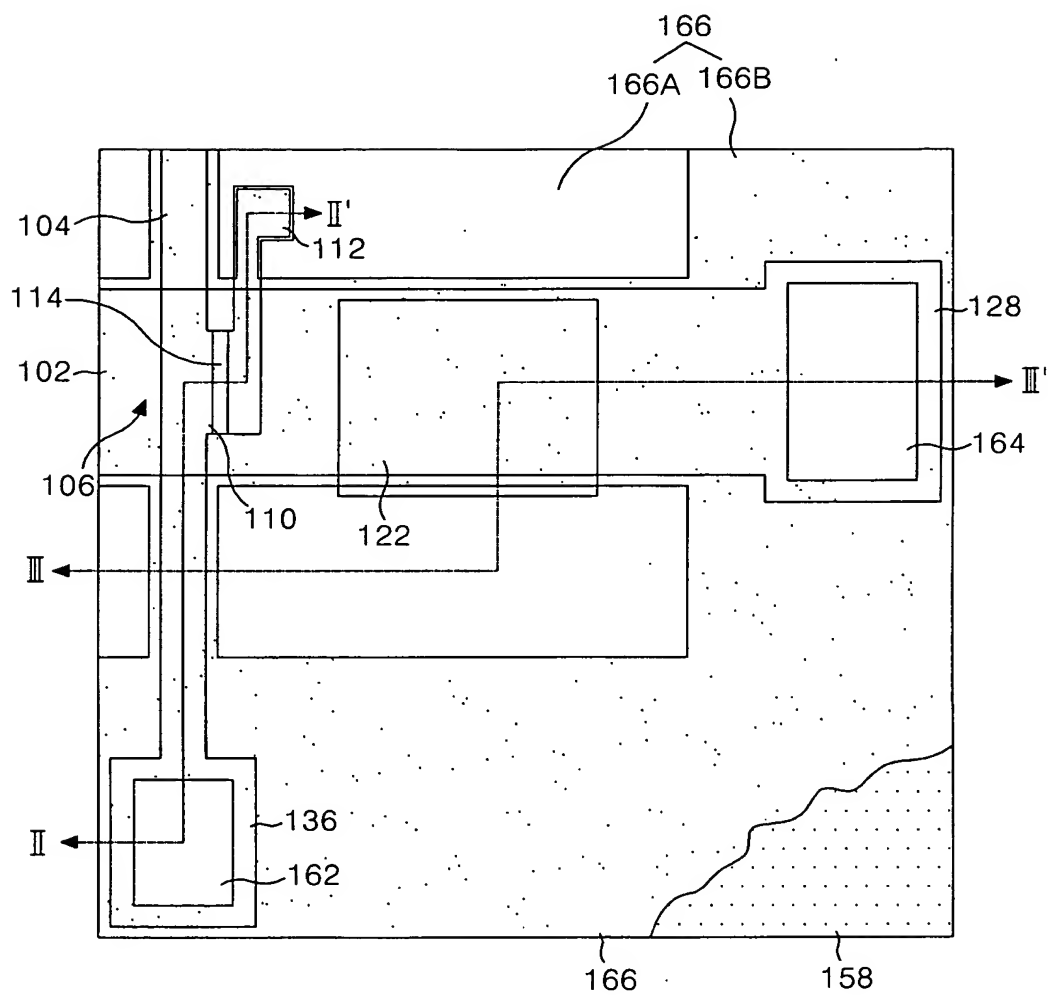


FIG. 12B

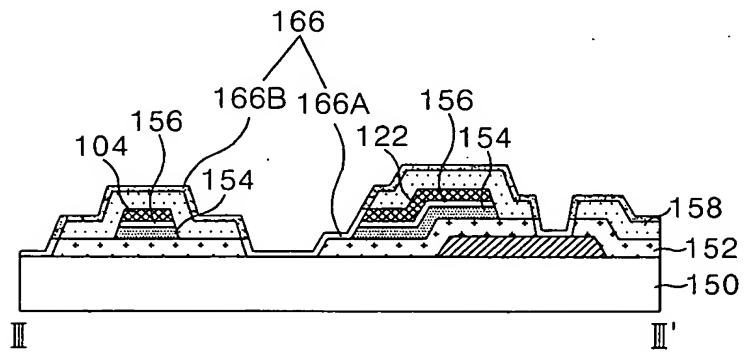
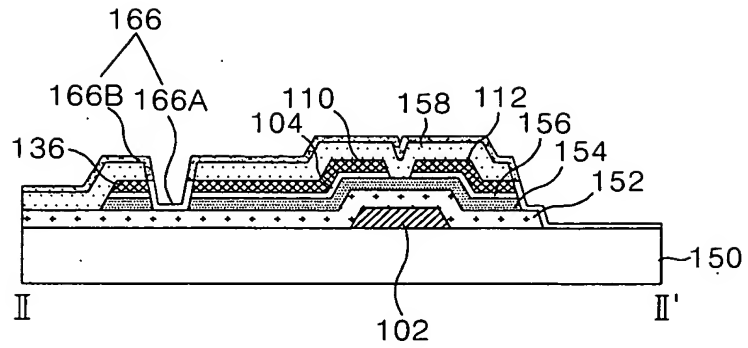


FIG. 13A

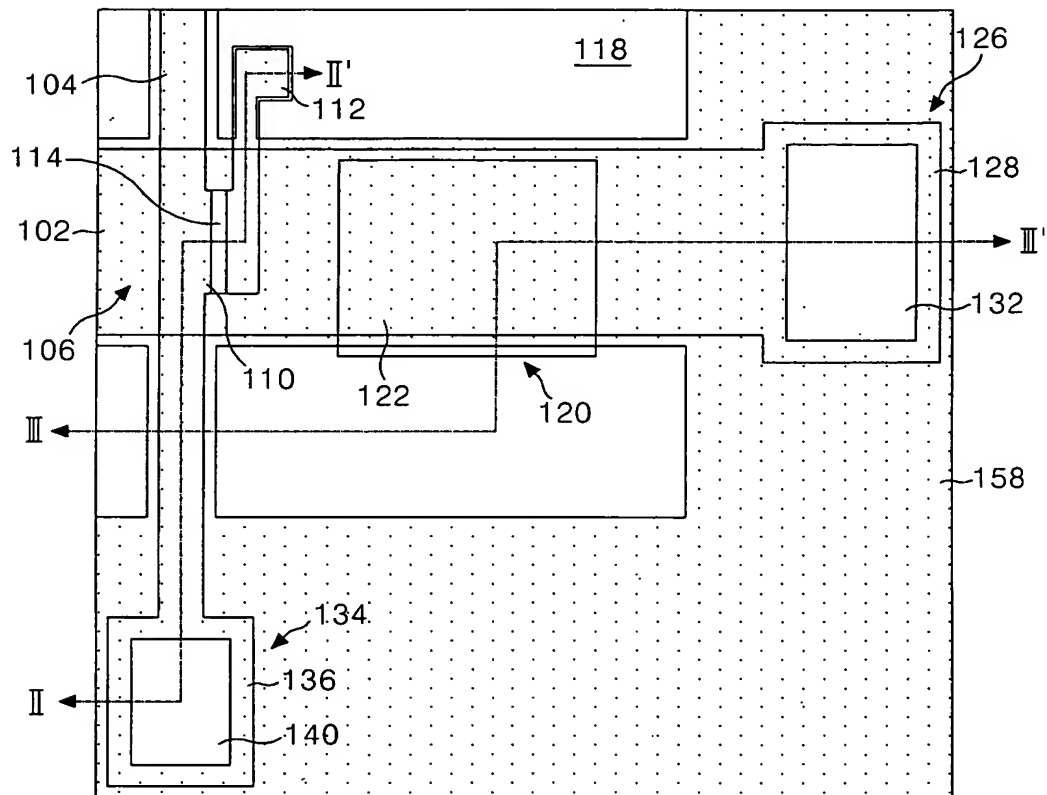


FIG. 13B

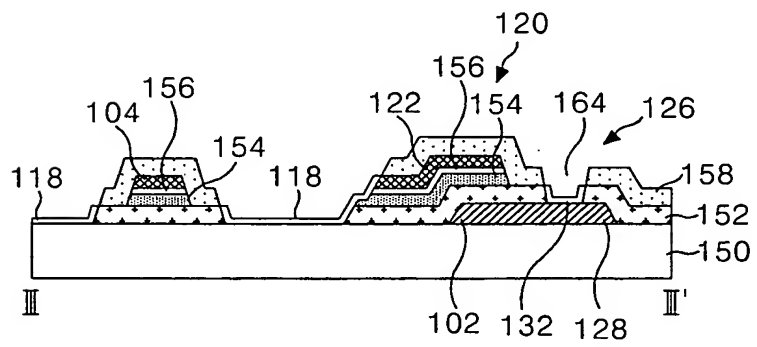
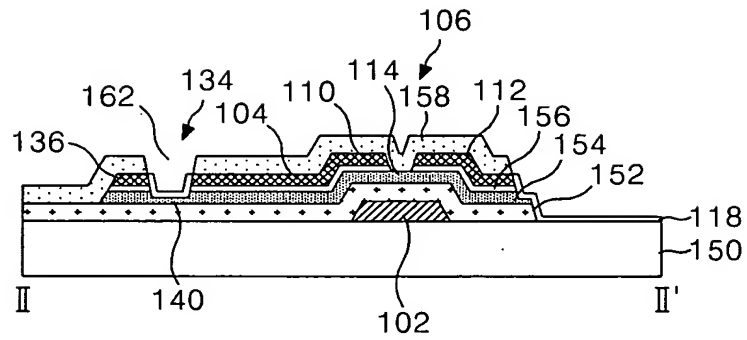


FIG. 14A

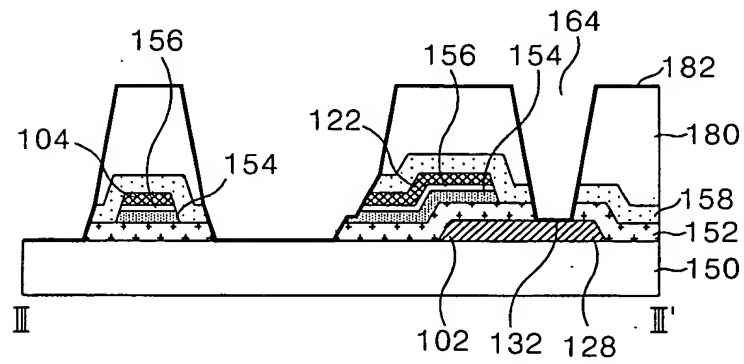
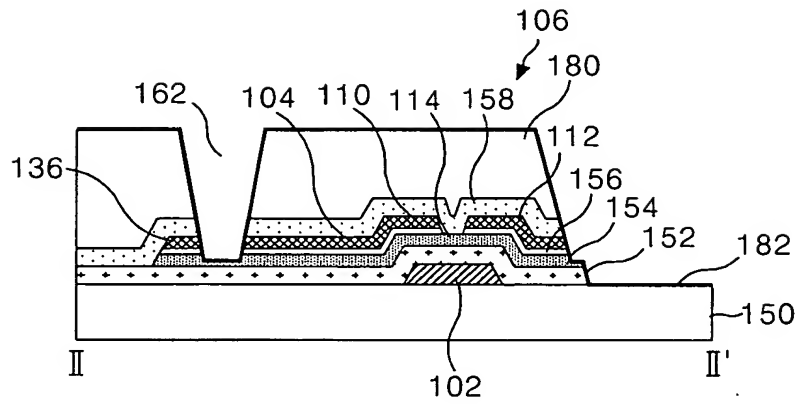


FIG. 14B

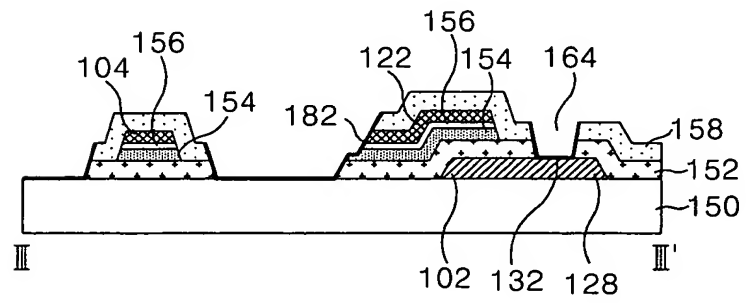
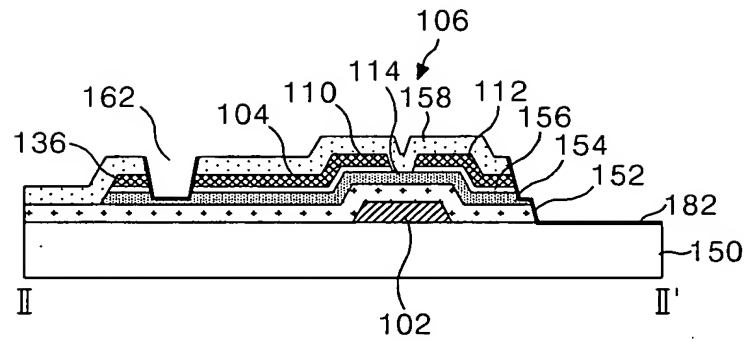


FIG. 14C

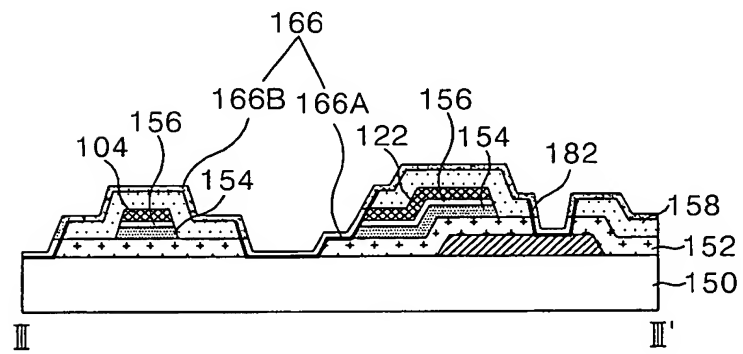
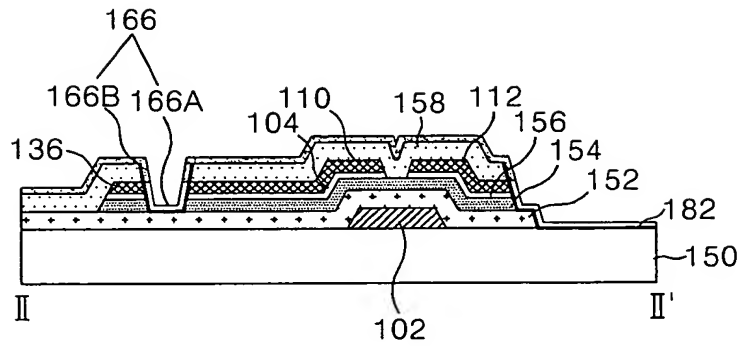


FIG. 14D

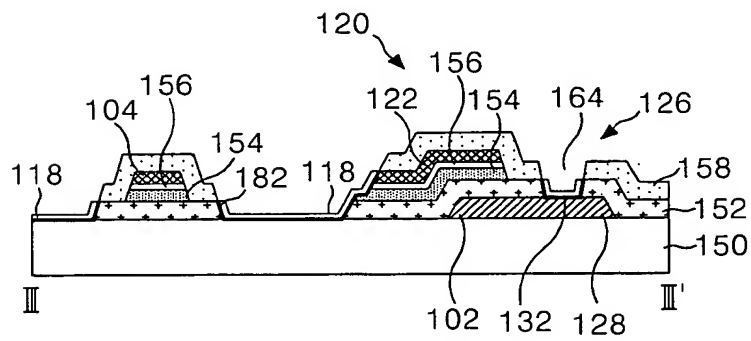
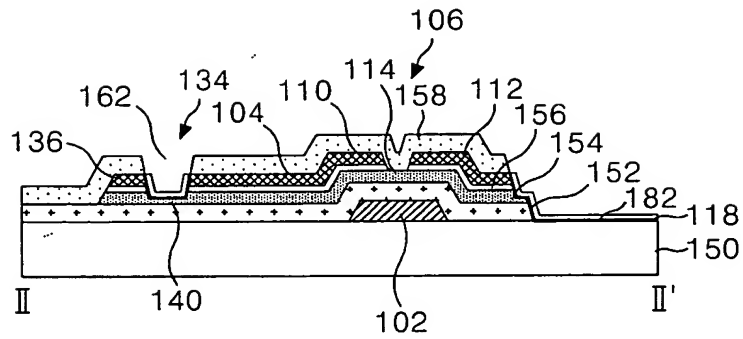


FIG. 15A

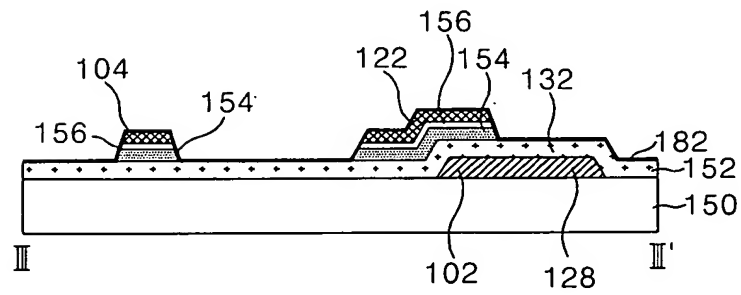
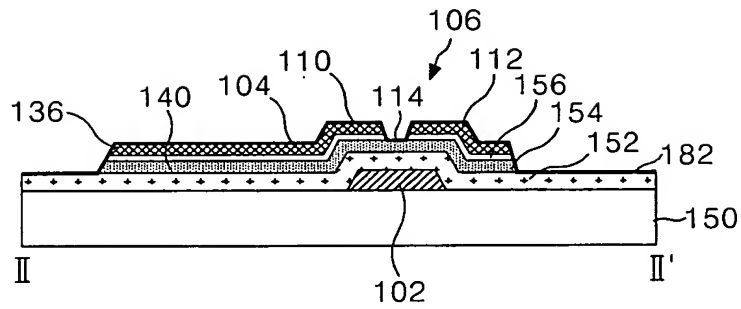


FIG. 15B

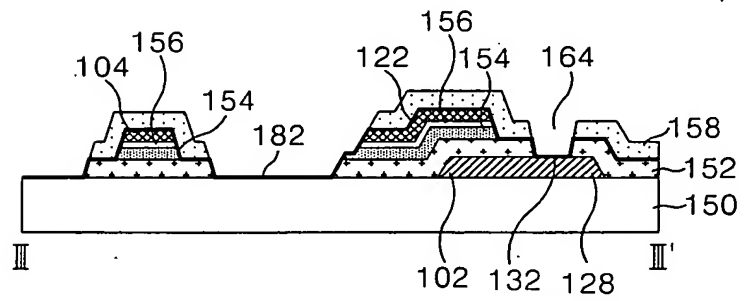
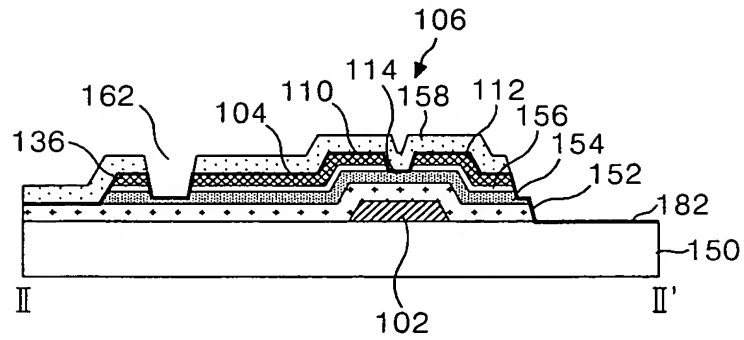
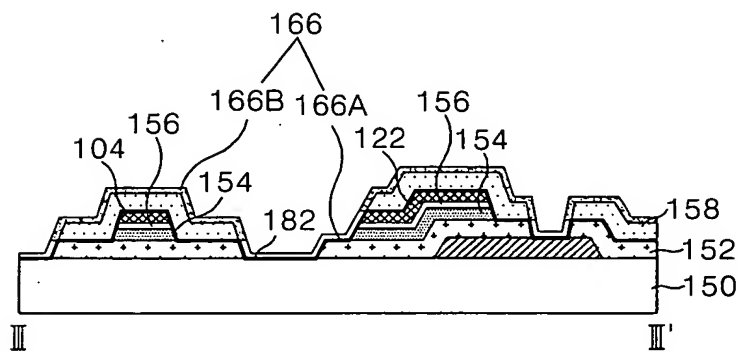
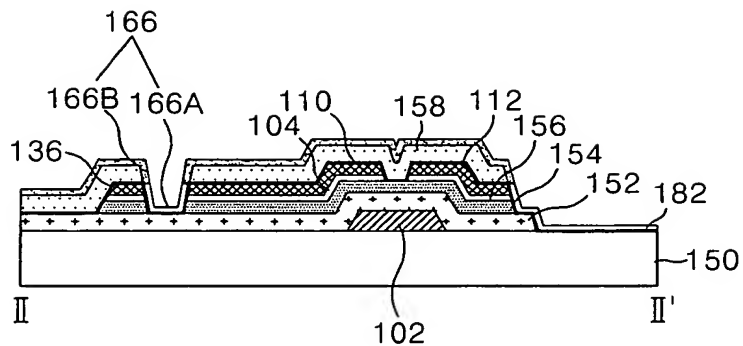


FIG. 15C



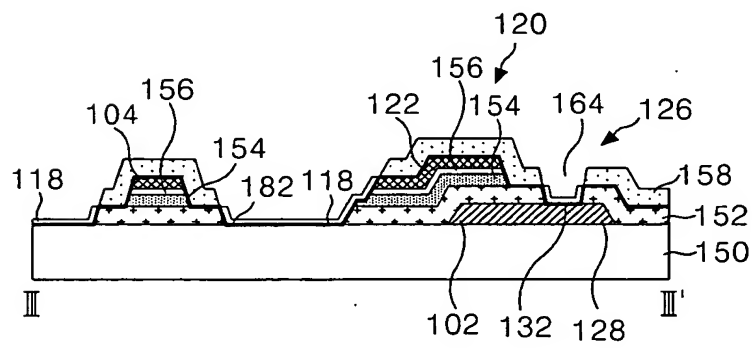


FIG. 16

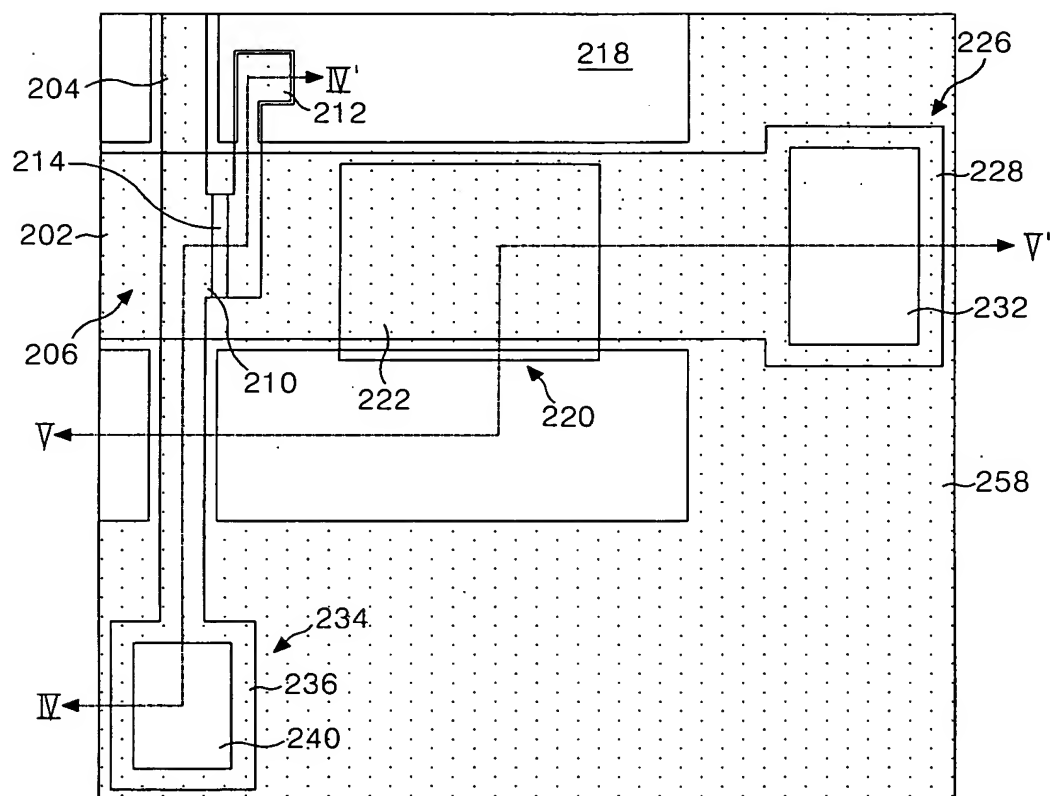


FIG.17

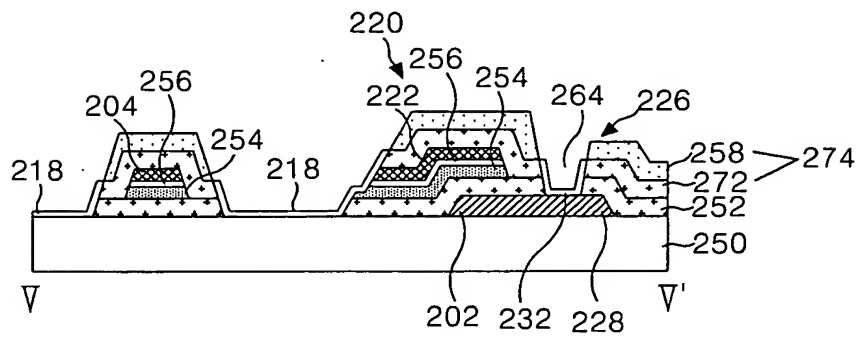
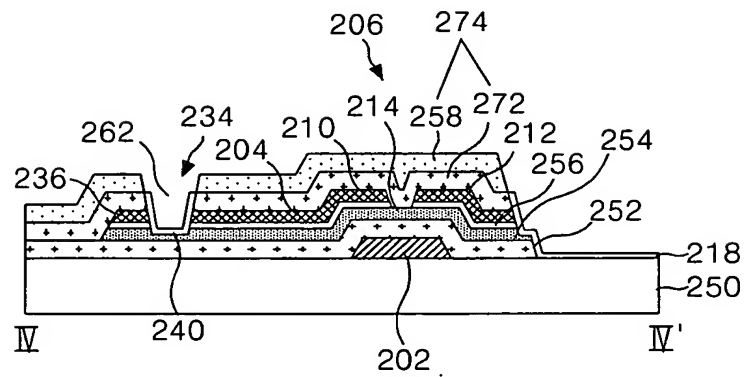


FIG. 18A

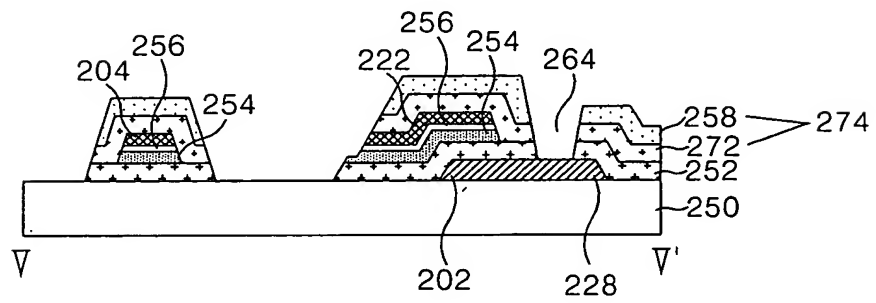
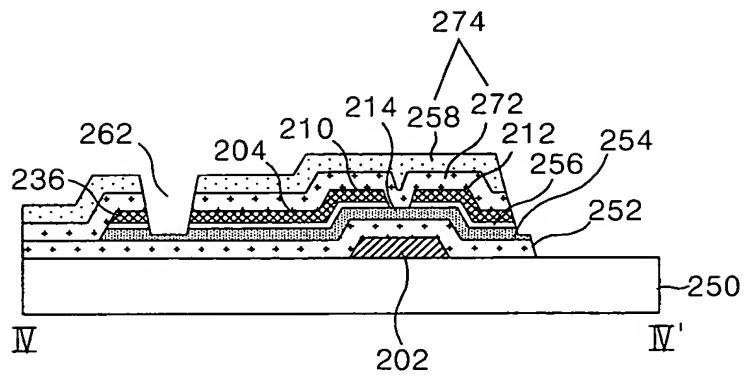
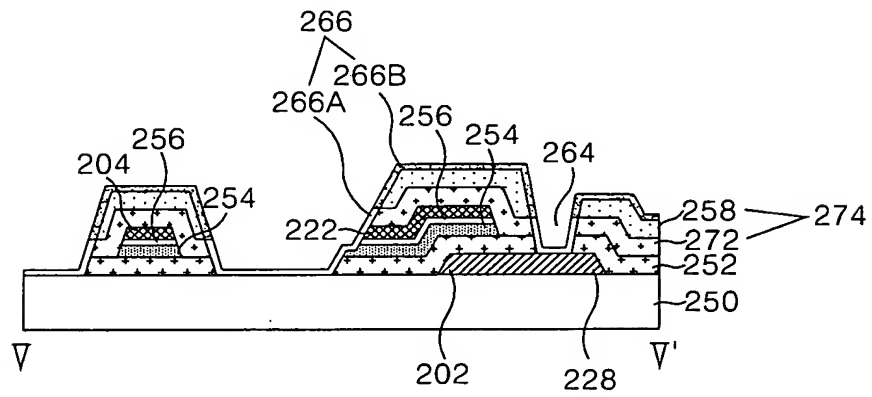
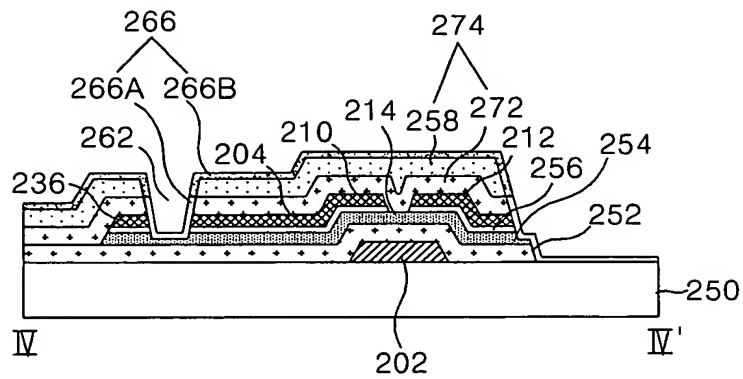


FIG. 18B



This cross-sectional view shows a substrate 250 with a base layer 218. A series of patterned layers are built on top, including a layer 202 with a central recessed area. Above this, there are multiple layers with different textures (dots, cross-hatch, diagonal lines) and a top layer 206. Various other layers and features are labeled with reference numerals: 236, 262, 234, 204, 210, 214, 258, 272, 274, 212, 256, 254, 252, and 240. The cross-section is taken along the line IV-IV'.

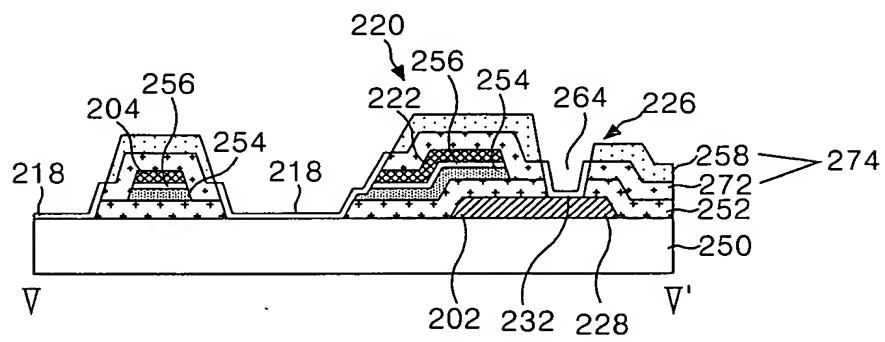


FIG. 19A

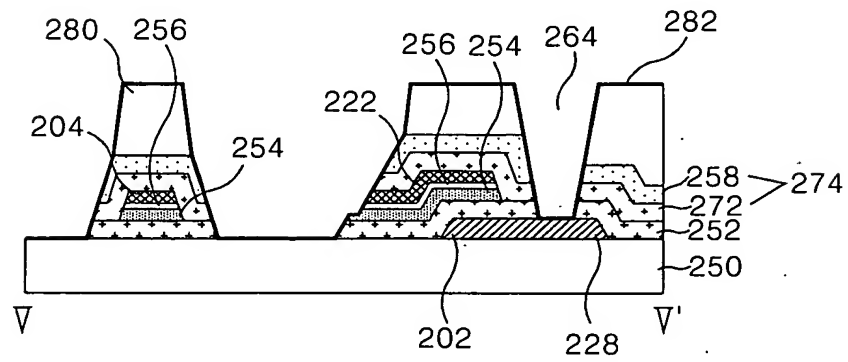
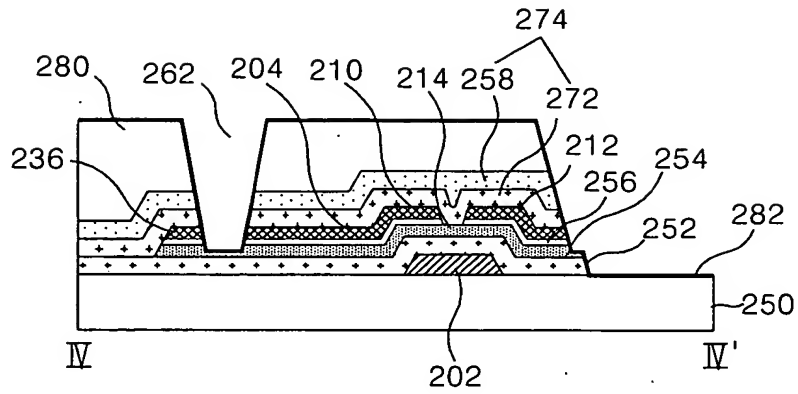


FIG. 19B

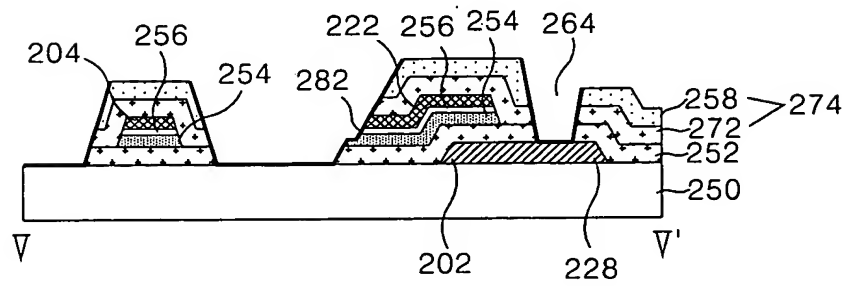
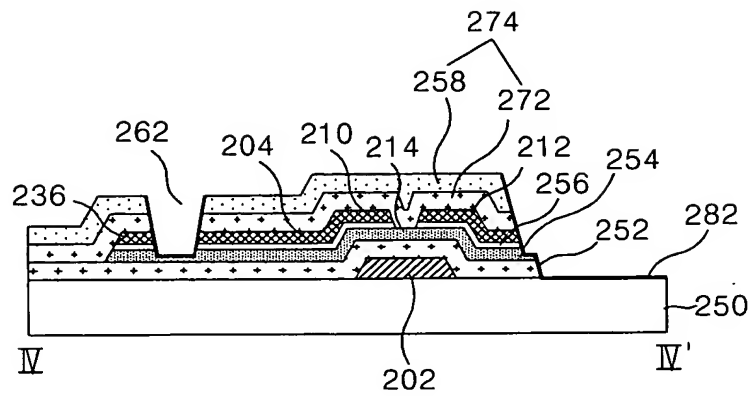


FIG. 19C

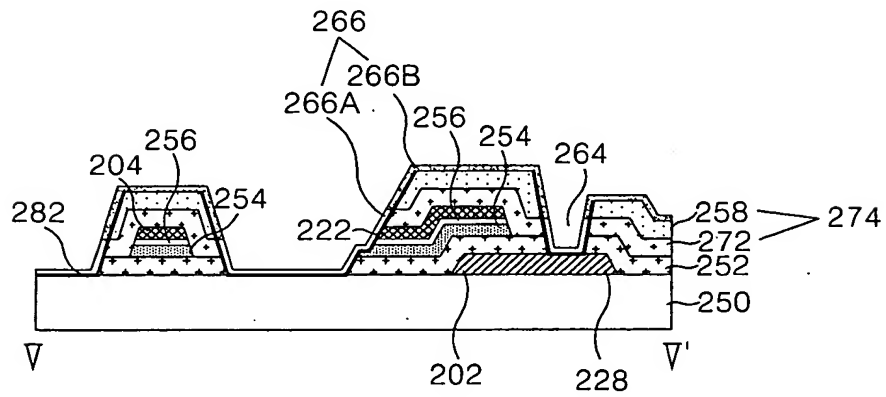
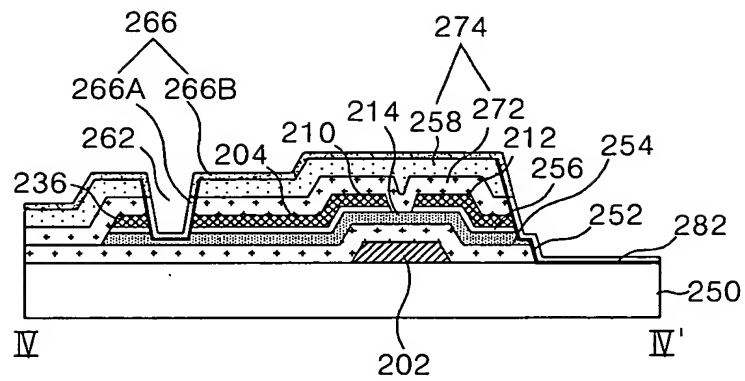


FIG. 19D

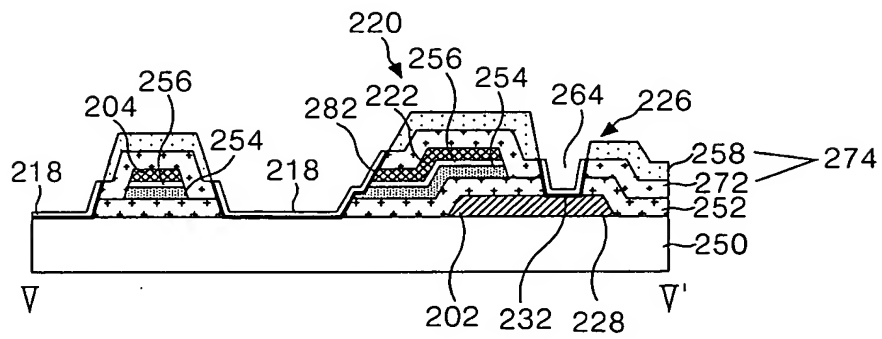
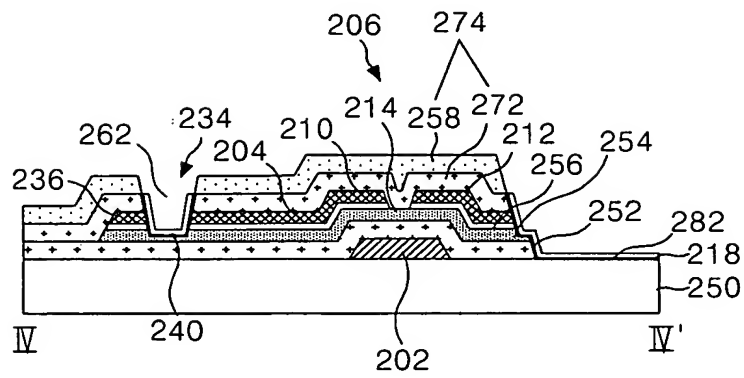


FIG. 20A

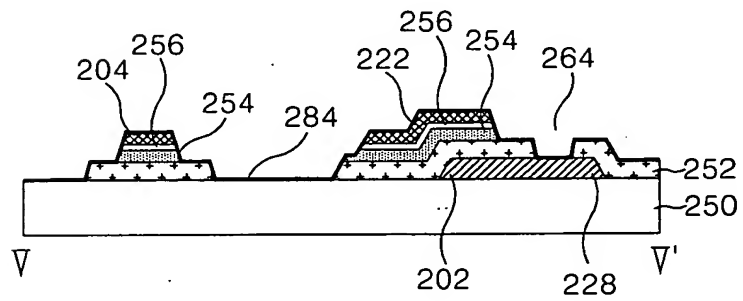
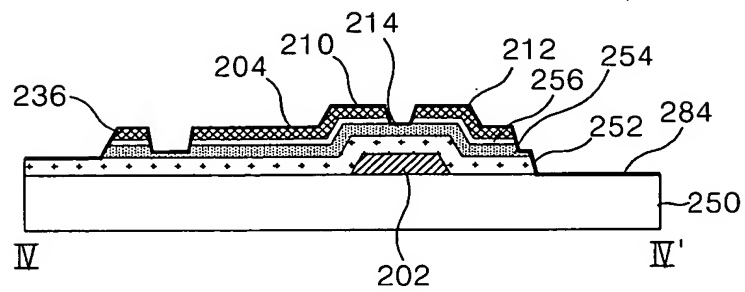


FIG. 20B

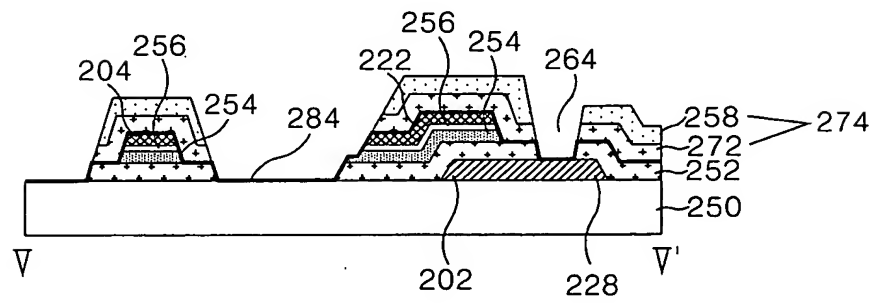
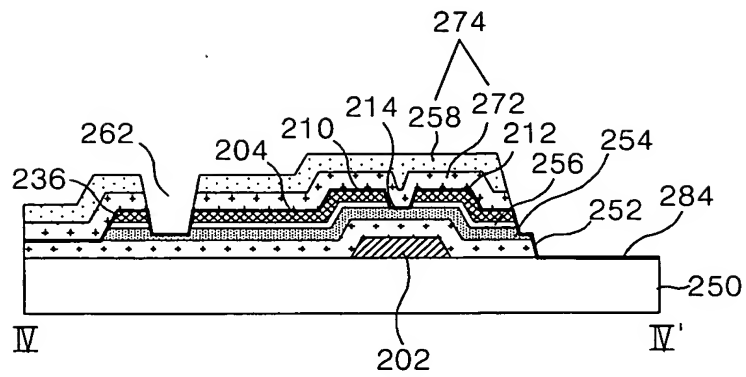


FIG. 20C

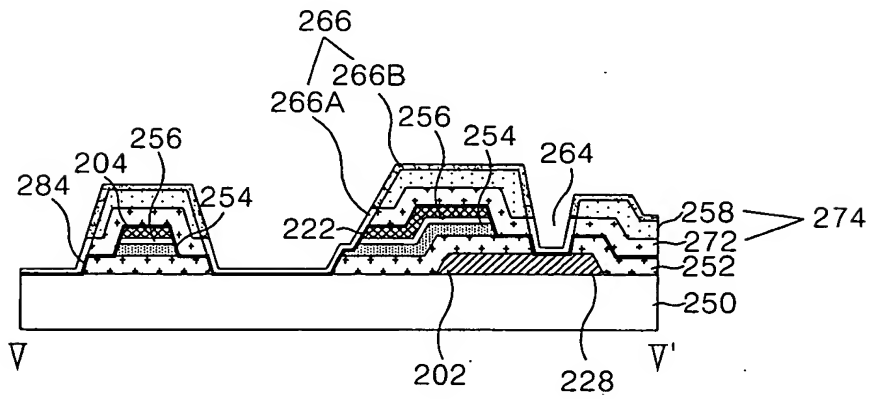
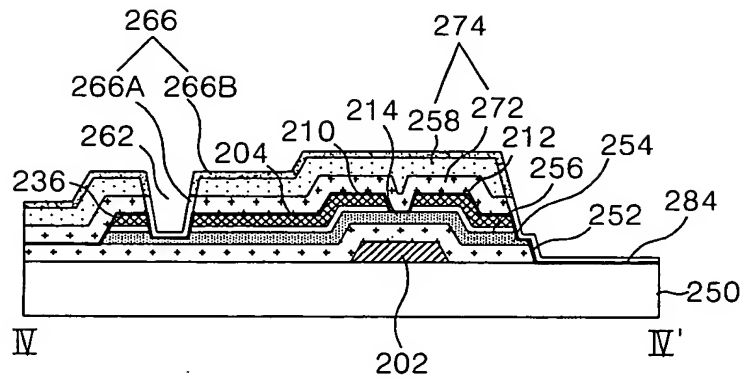


FIG. 20D

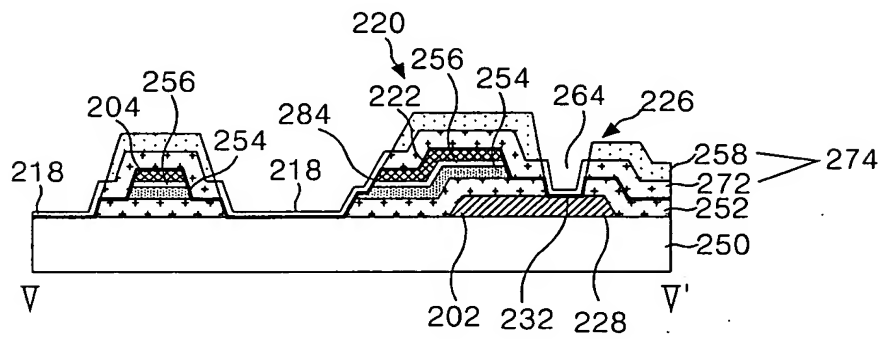
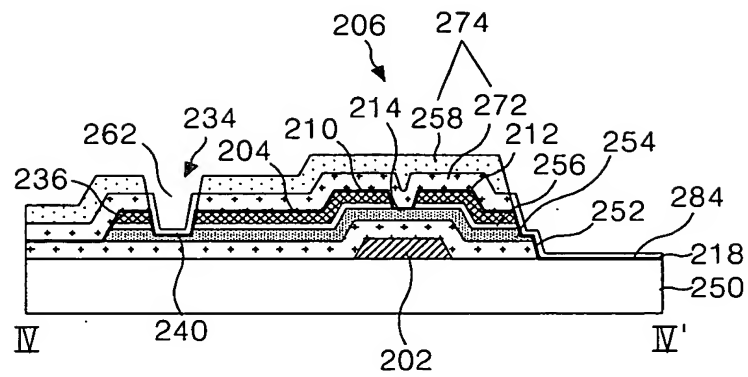


FIG. 21

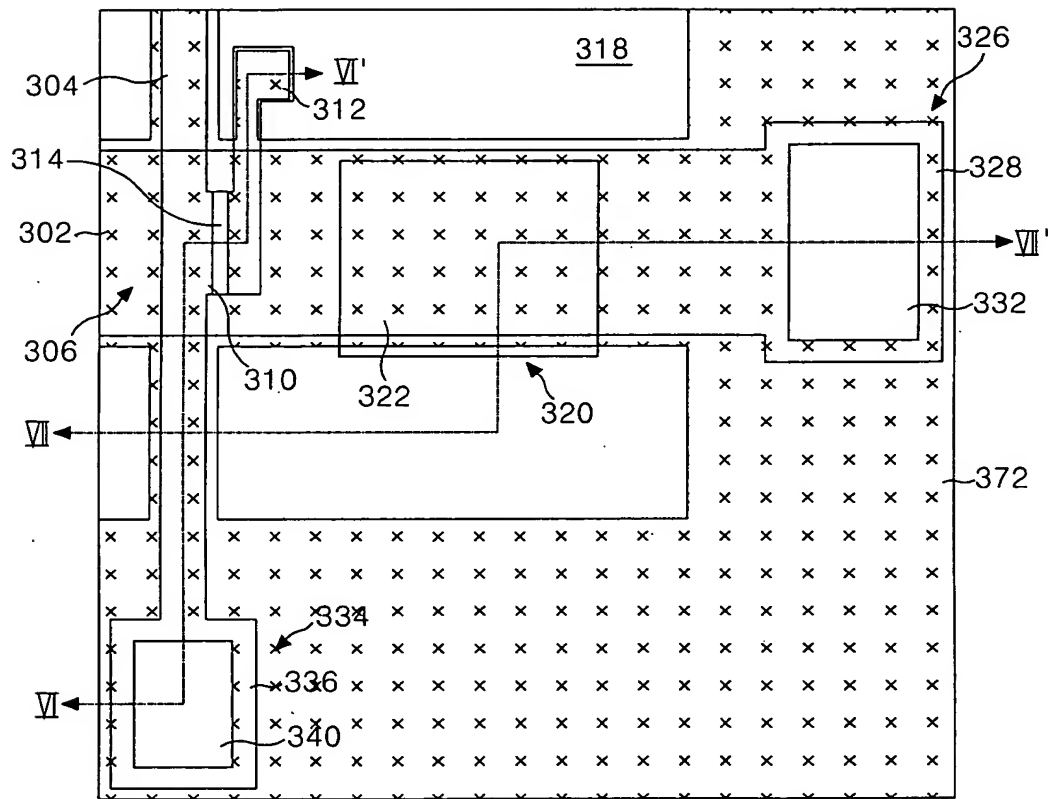


FIG. 22

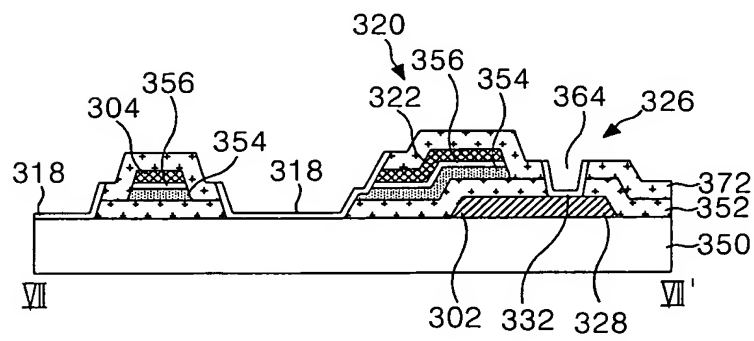
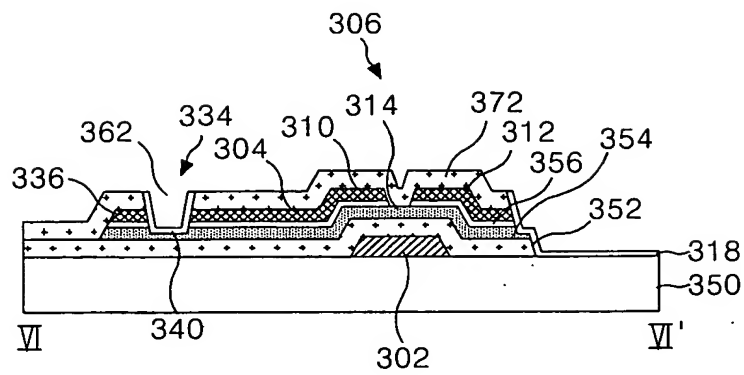


FIG. 23A

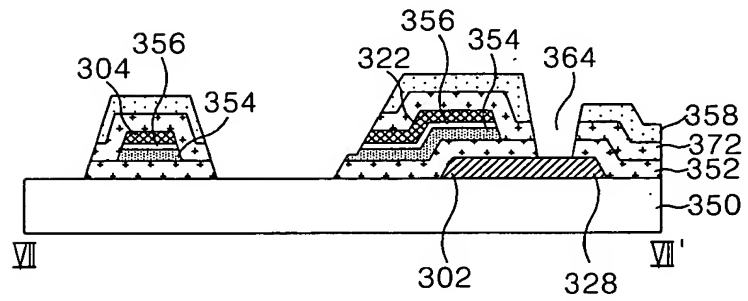
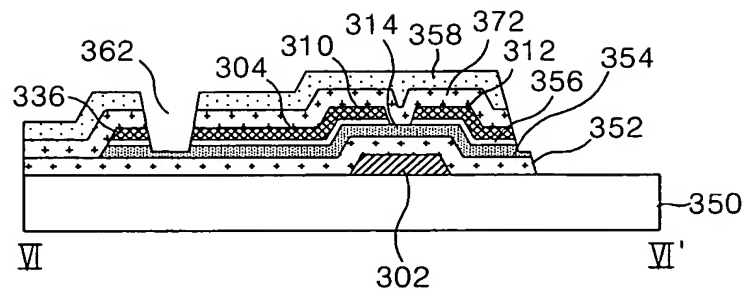


FIG. 23B

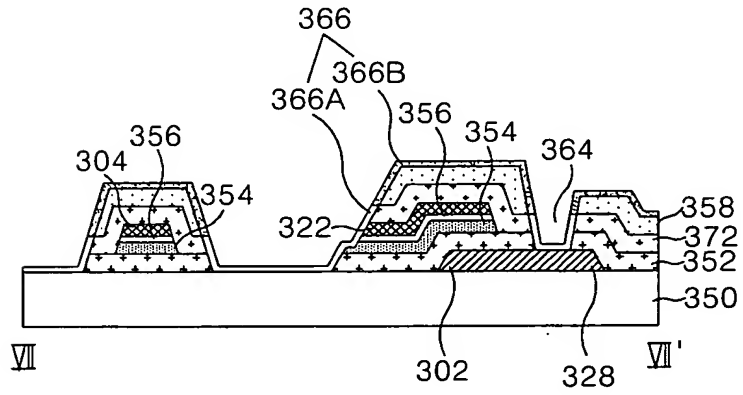
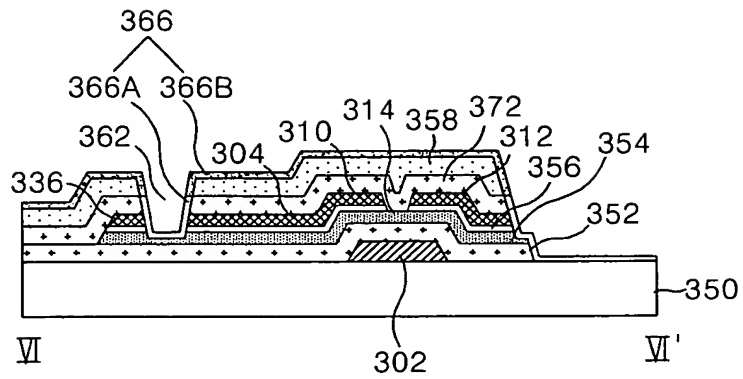


FIG. 23C

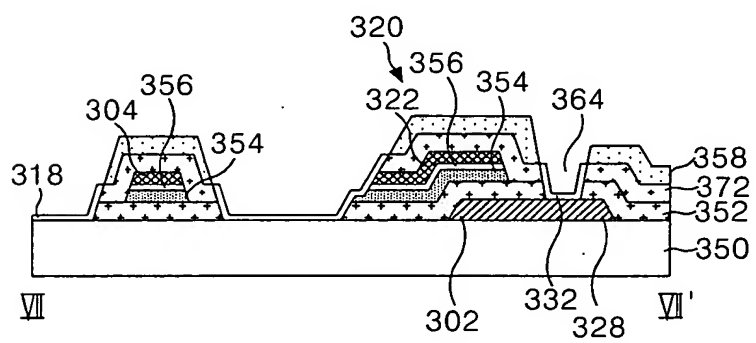
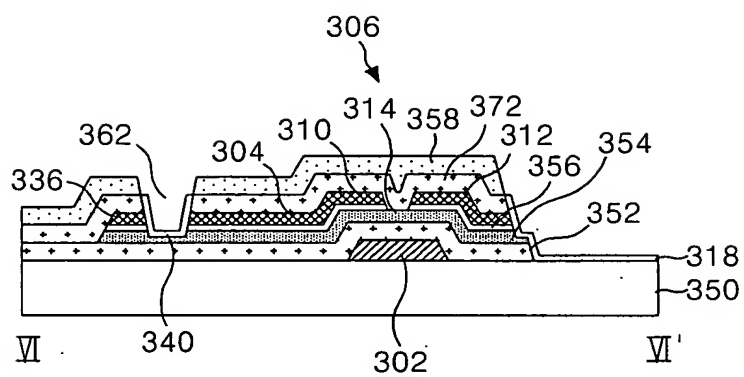


FIG. 23D

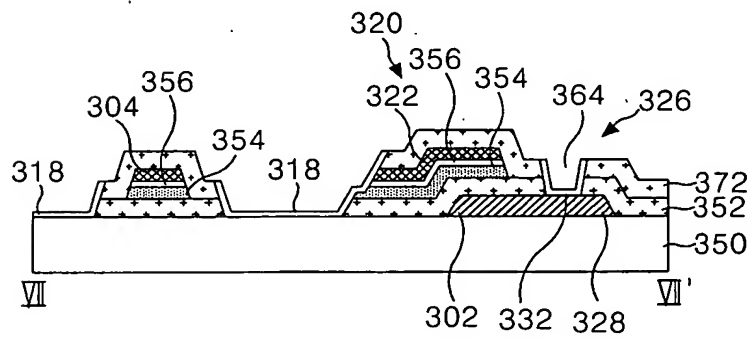
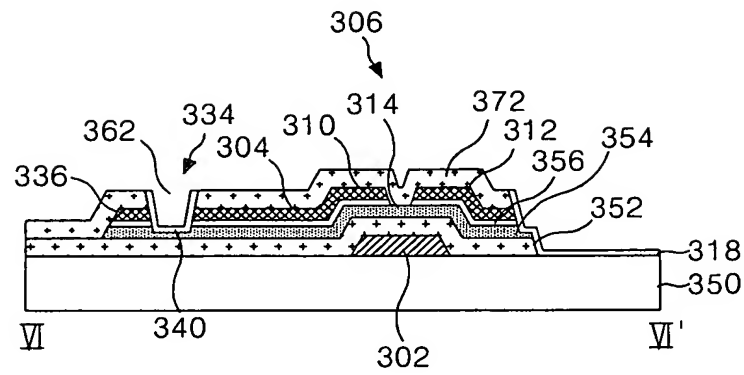


FIG. 24A

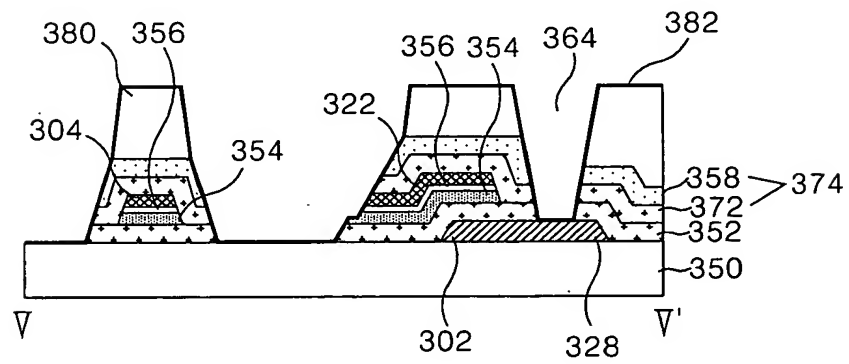
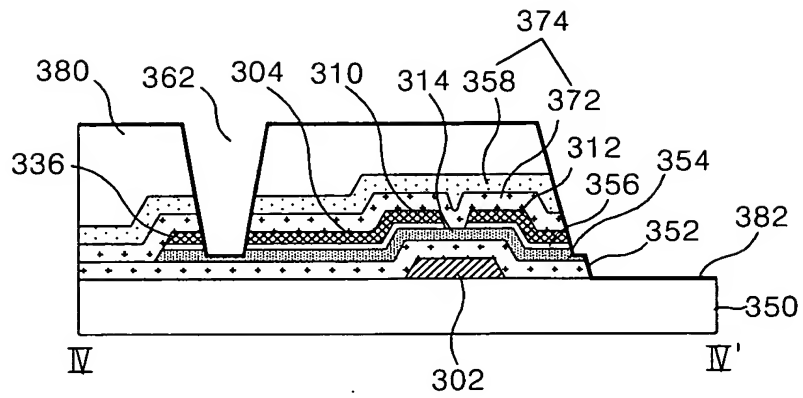


FIG. 24B

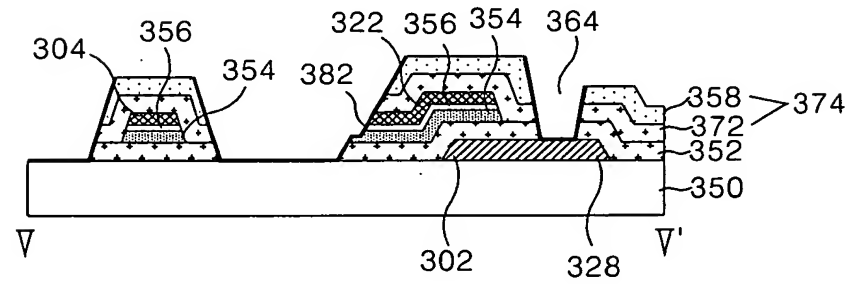
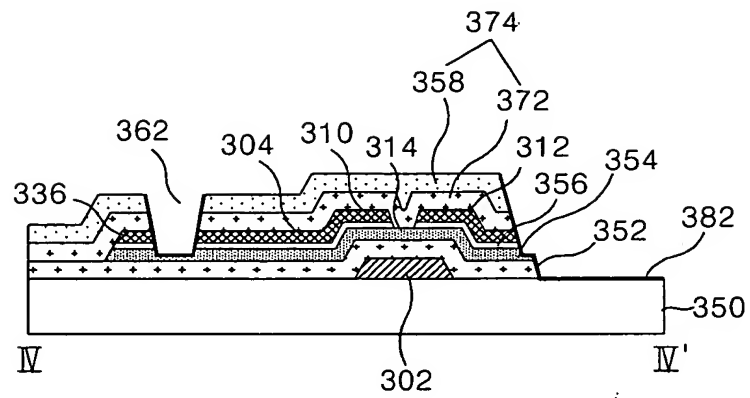


FIG. 24C

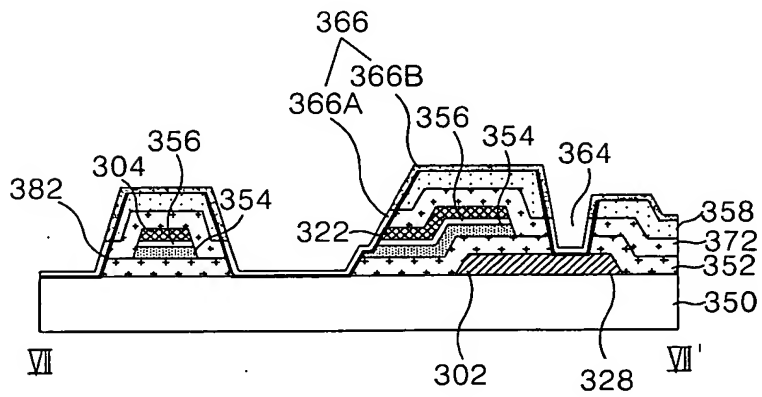
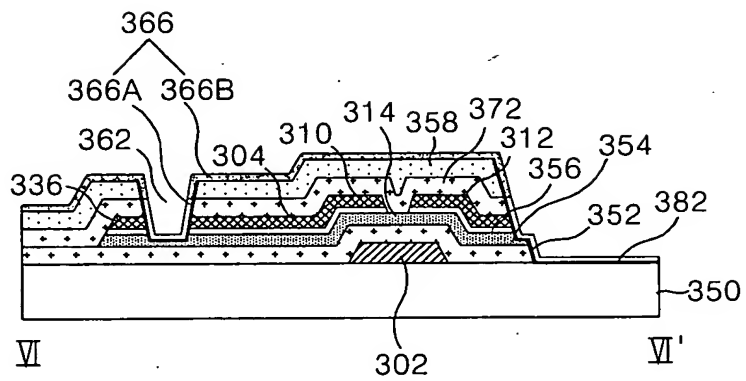


FIG. 24D

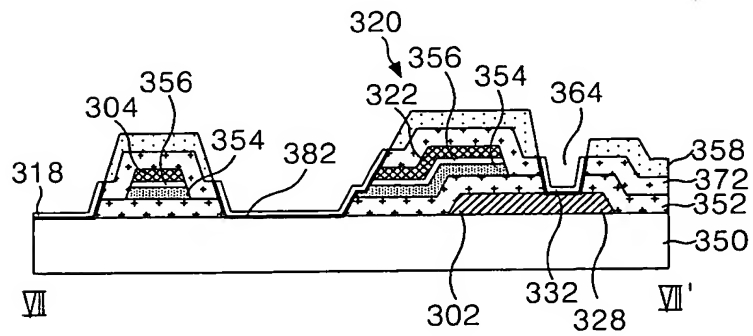
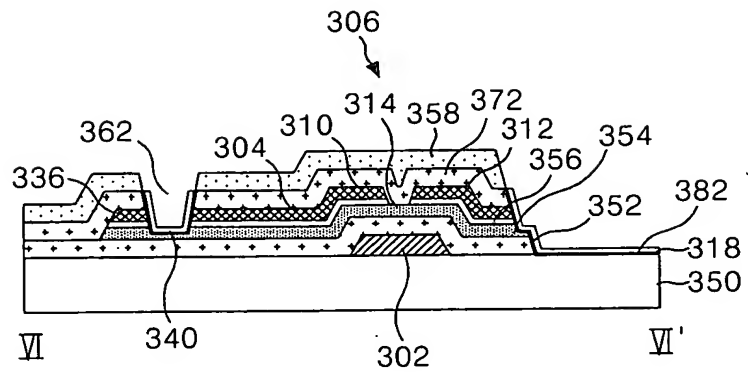


FIG. 24E

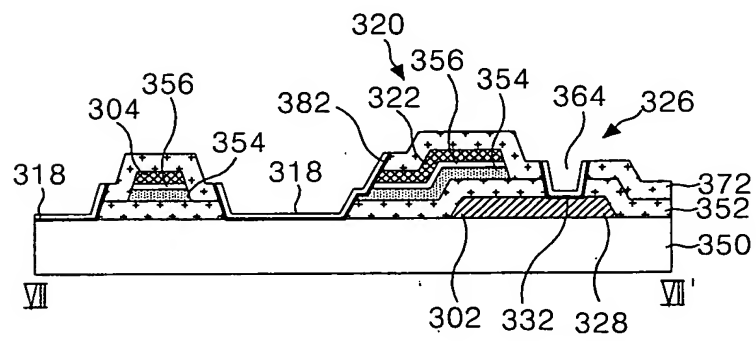
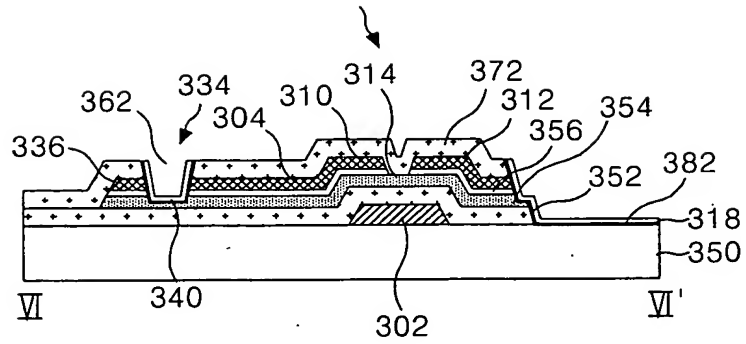


FIG. 25A

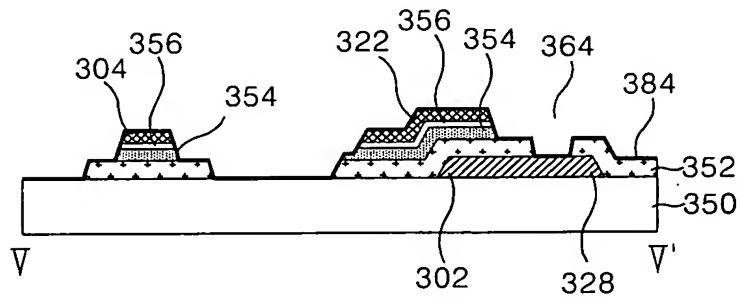
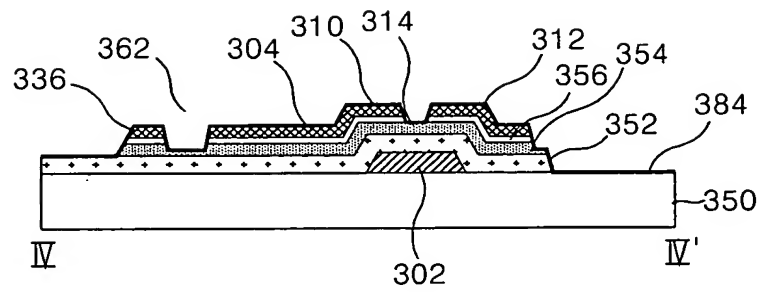


FIG. 25B

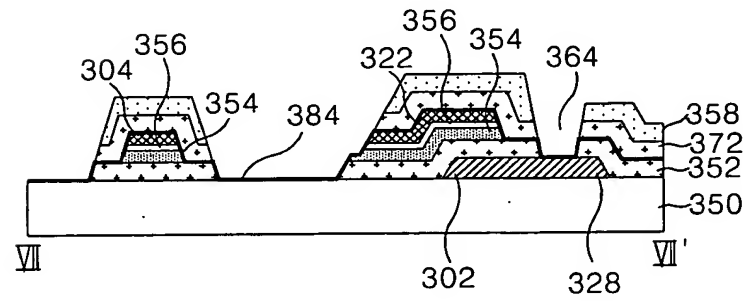
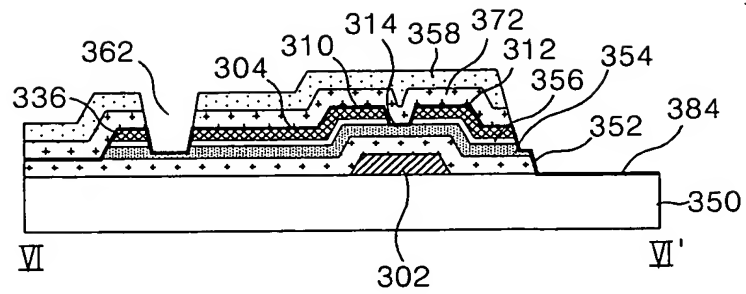


FIG. 25C

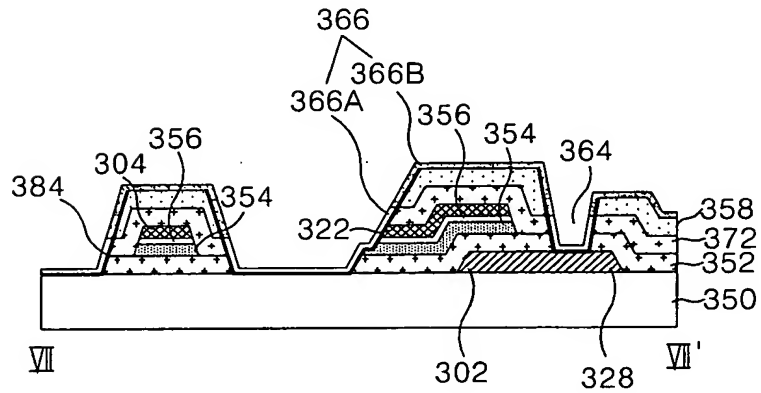
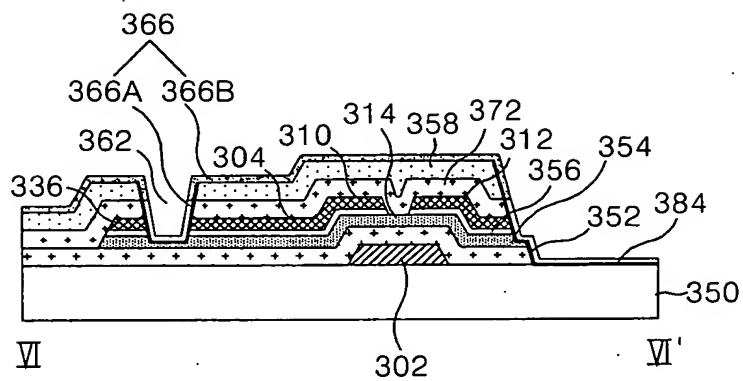


FIG. 25D

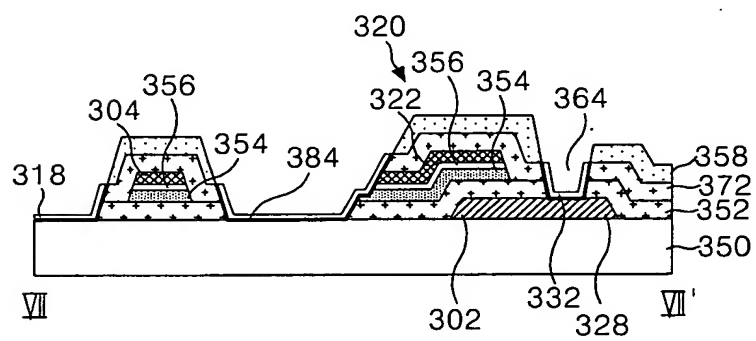
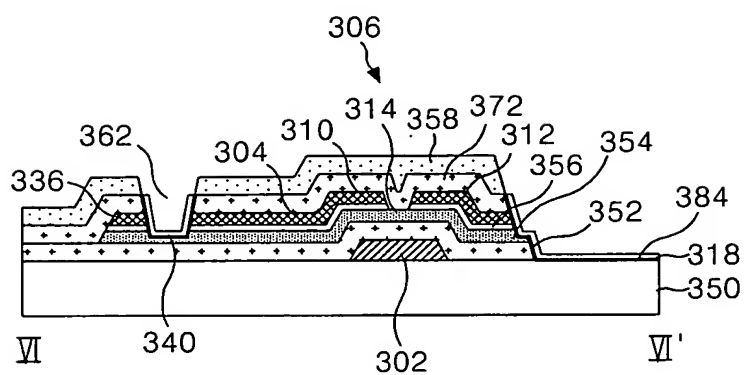


FIG. 25E

